

RCX700N20

Nch 200V 70A Power MOSFET

V_{DSS}	200V
R _{DS(on)} (Max.)	42.7m $Ω$
I _D	70A
P_D	83W

Features

- 1) Low on-resistance.
- 2) Fast switching speed.
- 3) Drive circuits can be simple.
- 4) Parallel use is easy.
- 5) Pb-free lead plating; RoHS compliant
- 6) 100% Avalanche tested

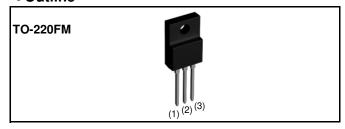
Application

Switching Power Supply

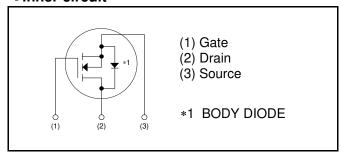
Automotive Motor Drive

Automotive Solenoid Drive

Outline



•Inner circuit



Packaging specifications

	Packaging	Bulk
	Reel size (mm)	1
Typo	Tape width (mm)	-
Туре	Quantity (pcs)	500
	Taping code	-
	Marking	RCX700N20

● Absolute maximum ratings (T_a = 25°C)

Parameter	Symbol	Value	Unit	
Drain - Source voltage		V_{DSS}	200	V
Continuous drain current	T _c = 25°C	I _D *1	±70	А
	$T_c = 100$ °C	I _D *1	±38	А
Pulsed drain current	I _{D,pulse} *2	±140	А	
Gate - Source voltage	V_{GSS}	±30	V	
Avalanche energy, single pulse		E _{AS} *3	396	mJ
Avalanche current		I _{AR} *3	35	Α
$T_c = 25^{\circ}C$		P _D	83	W
Power dissipation $T_a = 25^{\circ}C$		P _D	2.23	W
Junction temperature		T _j	150	°C
Range of storage temperature	T _{stg}	-55 to +150	°C	

●Thermal resistance

Parameter	Symbol	Values			Unit
Farameter	Symbol	Min.	Тур.	Max.	Offic
Thermal resistance, junction - case	R_{thJC}	-	-	1.49	°C/W
Thermal resistance, junction - ambient	R_{thJA}	-	-	56	°C/W
Soldering temperature, wavesoldering for 10s	T _{sold}	-	-	265	°C

• Electrical characteristics $(T_a = 25^{\circ}C)$

Parameter	Symbol	Conditions	Values			Unit
rarameter 	Syllibol	Conditions	Min.	Тур.	Max.	Offic
Drain - Source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V$, $I_D = 1mA$	200	-	-	V
		$V_{DS} = 200V, V_{GS} = 0V$			25	
Zara gata valtaga drain aurrant	,	$T_j = 25^{\circ}C$	-	-	25	μΑ
Zero gate voltage drain current	I _{DSS}	$V_{DS} = 200V, V_{GS} = 0V$	-		100	
		T _j = 125°C				
Gate - Source leakage current	I _{GSS}	$V_{GS} = \pm 30V, \ V_{DS} = 0V$	-	ı	±100	nA
Gate threshold voltage	V _{GS (th)}	$V_{DS} = 10V$, $I_D = 1mA$	3.0	ı	5.0	V
		$V_{GS} = 10V, I_D = 35A$	-	30.5	42.7	
Static drain - source on - state resistance	R _{DS(on)} *4	$V_{GS} = 10V, I_D = 35A$		62.0	87.0	mΩ
		T _j = 125°C	_	02.0	07.0	
Forward transfer admittance	g_{fs}	$V_{DS} = 10V, I_D = 35A$	15.3	30.6	-	S

●Electrical characteristics (T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
r ai ainietei	Syllibol	Conditions	Min.	Тур.	Max.	Offic
Input capacitance	C_{iss}	$V_{GS} = 0V$	-	6900	-	
Output capacitance	C _{oss}	V _{DS} = 25V	-	400	-	pF
Reverse transfer capacitance	C_{rss}	f = 1MHz	-	230	-	
Turn - on delay time	t _{d(on)} *4	$V_{DD} \simeq 100V, V_{GS} = 10V$	-	70	-	
Rise time	t _r *4	$I_D = 35A$	-	340	-	no
Turn - off delay time	t _{d(off)} *4	$R_L = 2.8\Omega$	-	160	-	ns
Fall time	t _f *4	$R_G = 10\Omega$	-	160	-	

● Gate Charge characteristics (T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
r arameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Total gate charge	Q_g^{*4}	$V_{DD} \simeq 100V$	-	125	-	
Gate - Source charge	Q _{gs} *4	$I_D = 70A$	-	40	ı	nC
Gate - Drain charge	Q _{gd} *4	$V_{GS} = 10V$	-	50	1	
Gate plateau voltage	$V_{(plateau)}$	$V_{DD} \simeq 100V, I_D = 70A$	-	7.0	-	V

●Body diode electrical characteristics (Source-Drain)(T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
i arameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Continuous source current	I _S *1	T _c = 25°C	-	ı	70	Α
Pulsed source current	I _{SM} *2	1 _c = 25 0	-	ı	140	Α
Forward voltage	V _{SD} *4	$V_{GS} = 0V, I_S = 70A$	-	-	1.5	V
Reverse recovery time	t _{rr} *4	I _S = 35A	-	130	-	ns
Reverse recovery charge	Q _{rr} *4	di/dt = 100A/μs	-	565	-	nC

^{*1} Limited only by maximum temperature allowed.

^{*2} Pw \leq 10 μ s, Duty cycle \leq 1%

^{*3} L $^{\simeq}$ 500 μ H, V_{DD} = 50V, Rg = 25 Ω , starting T_{j} = 25°C

^{*4} Pulsed

Fig.1 Power Dissipation Derating Curve

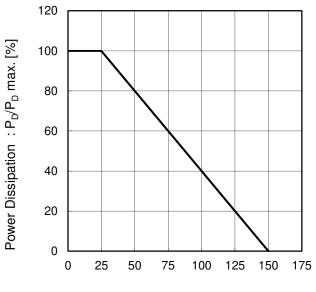
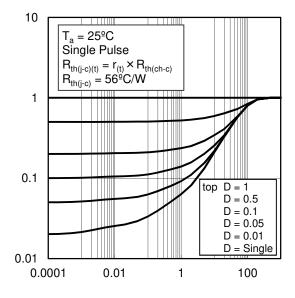


Fig.2 Normalized Transient Thermal Resistance vs. Pulse Width



Pulse Width: Pw [s]

Normalized Transient Thermal Resistance: r(t)

Fig.3 Avalanche Current vs Inductive Load

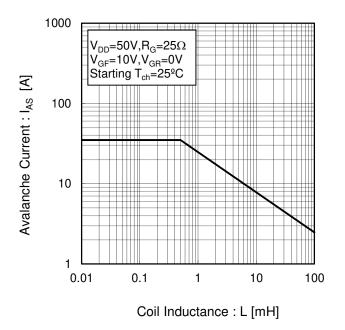


Fig.4 Avalanche Energy Derating Curve vs Junction Temperature

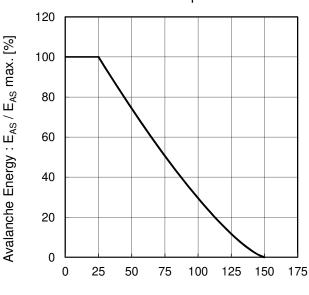
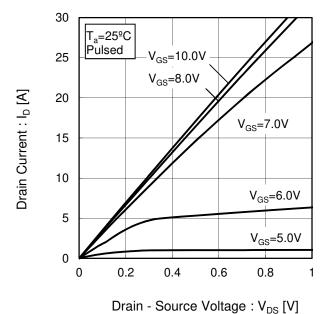


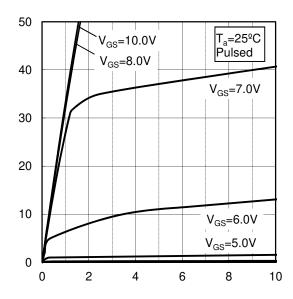
Fig.5 Typical Output Characteristics(I)



Drain Current : I_D [A]

Fig.6 Typical Output Characteristics(II)

Junction Temperature : T_i [°C]



Drain - Source Voltage : V_{DS} [V]

Fig.7 Breakdown Voltage vs. Junction Temperature 280 Normarize Drain - Source Breakdown Voltage $V_{GS} = 0V$ 270 $I_D = 1 \text{mA}$ 260 250 240 : V_{(BR)DSS} [V] 230 220 210 200 190 180 -50 0 50 100 150 Junction Temperature : T_i [°C]

100 **V**_{DS}= 10**V** 10 Drain Current: I_D [A] 0.1 T_a= 125ºC $T_a^a = 75^{\circ}C$ $T_a^a = 25^{\circ}C$ 0.01 $T_a = -25^{\circ}C$ 0.001 0 2 3 4 5 6 8 9 10

Fig.8 Typical Transfer Characteristics

Fig.9 Gate Threshold Voltage vs. Junction Temperature

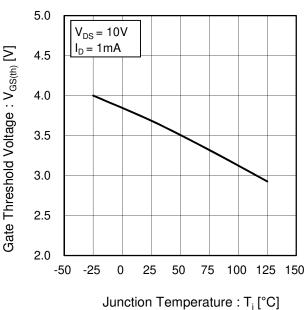
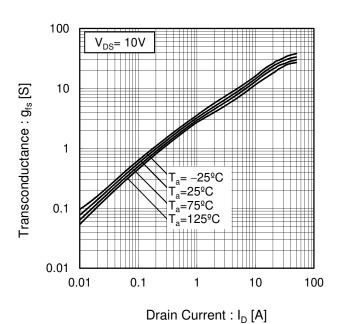


Fig.10 Transconductance vs. Drain Current

Gate - Source Voltage : V_{GS} [V]



100

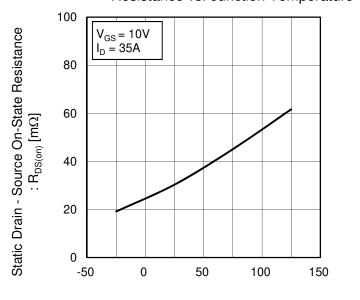
Drain Current: I_D [A]

• Electrical characteristic curves

Fig.11 Static Drain - Source On - State Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage Resistance vs. Drain Current(I) 100 1000 Static Drain - Source On-State Resistance Static Drain - Source On-State Resistance T_a=25°C T_a=25ºC 80 $V_{GS} = 10V$ $I_D = 35A$ 100 60 $:R_{DS(on)}\left[m\Omega \right]$ $I_D = 50A$ $:R_{\text{DS}(\text{on})}\left[\text{m}\Omega\right]$ 40 10 20 0 0 5 10 15 20 0.01 0.1 1 10

Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature

Gate - Source Voltage : $V_{GS}[V]$



Junction Temperature : T_j [${}^{\circ}C$]

Fig.14 Static Drain - Source On - State Resistance vs. Drain Current(I) 1000 $V_{GS} = 10V$ =125ºC =75ºC a=25ºC

Static Drain - Source On-State Resistance 100 -25ºC $:R_{\text{DS(on)}}\left[m\Omega \right]$ 10

0.1

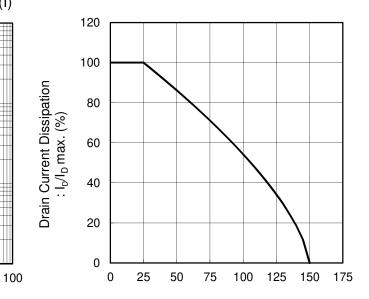
0.01

Drain Current : I_D [A]

1

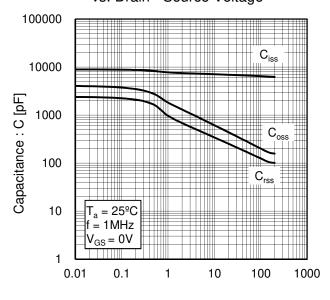
10

Fig.15 Drain Current Derating Curve



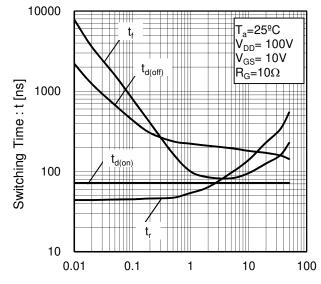
Junction Temperature : T_j [${}^{\circ}C$]

Fig.16 Typical Capacitance vs. Drain - Source Voltage



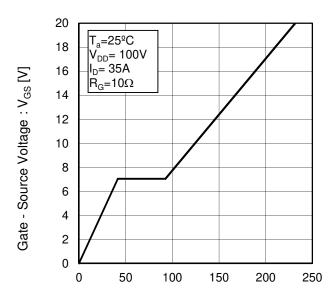
Drain - Source Voltage : V_{DS} [V]

Fig.17 Switching Characteristics

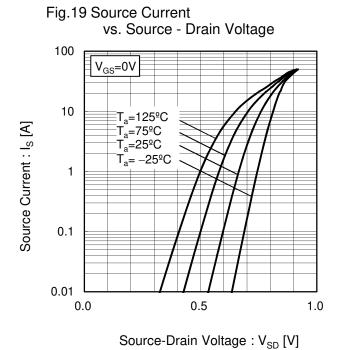


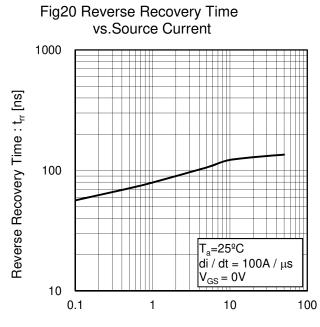
Drain Current : I_D [A]

Fig.18 Dynamic Input Characteristics



Total Gate Charge : Q_g [nC]





Source Current : I_S [A]

Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

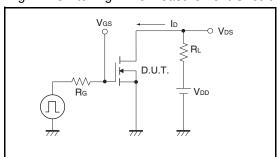


Fig.2-1 Gate Charge Measurement Circuit

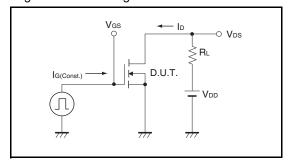


Fig.3-1 Avalanche Measurement Circuit

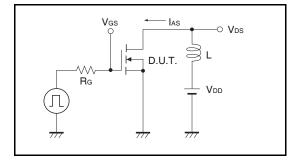


Fig.1-2 Switching Waveforms

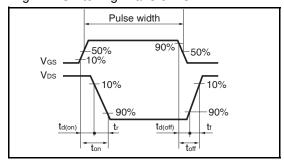


Fig.2-2 Gate Charge Waveform

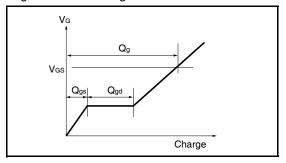
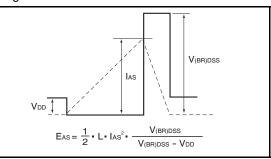
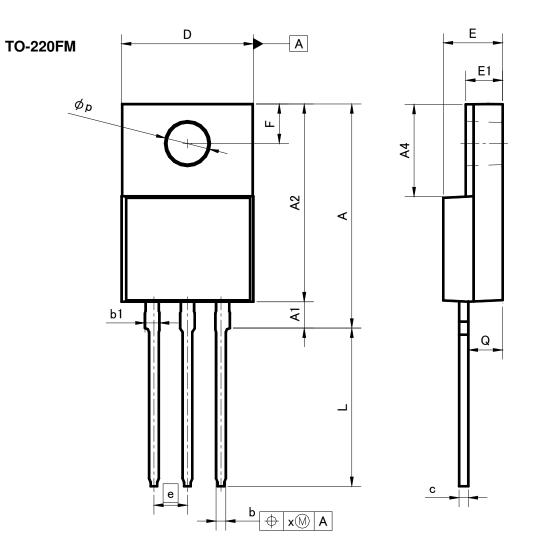


Fig.3-2 Avalanche Waveform



● **Dimensions** (Unit: mm)



DIM	MILIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
Α	16.60	17.60	0.654	0.693
A1	1.80	2.20	0.071	0.087
A2	14.80	15.40	0.583	0.606
A4	6.80	7.20	0.268	0.283
b	0.70	0.85	0.028	0.033
b1	1.10	1.50	0.043	0.059
С	0.70	0.85	0.028	0.033
D	9.90	10.30	0.390	0.406
E	4.40	4.80	0.173	0.189
е	2.54		0.1	00
E1	2.70	3.00	0.106	0.118
F	2.80	3.20	0.110	0.126
L	11.50	12.50	0.453	0.492
р	3.00	3.40	0.118	0.134
Q	2.10	3.10	0.083	0.122
х	_	0.38	_	0.015

Dimension in mm / inches

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CLASSIV	CLASSII	CLASSⅢ	CLASSⅢ

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 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
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 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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